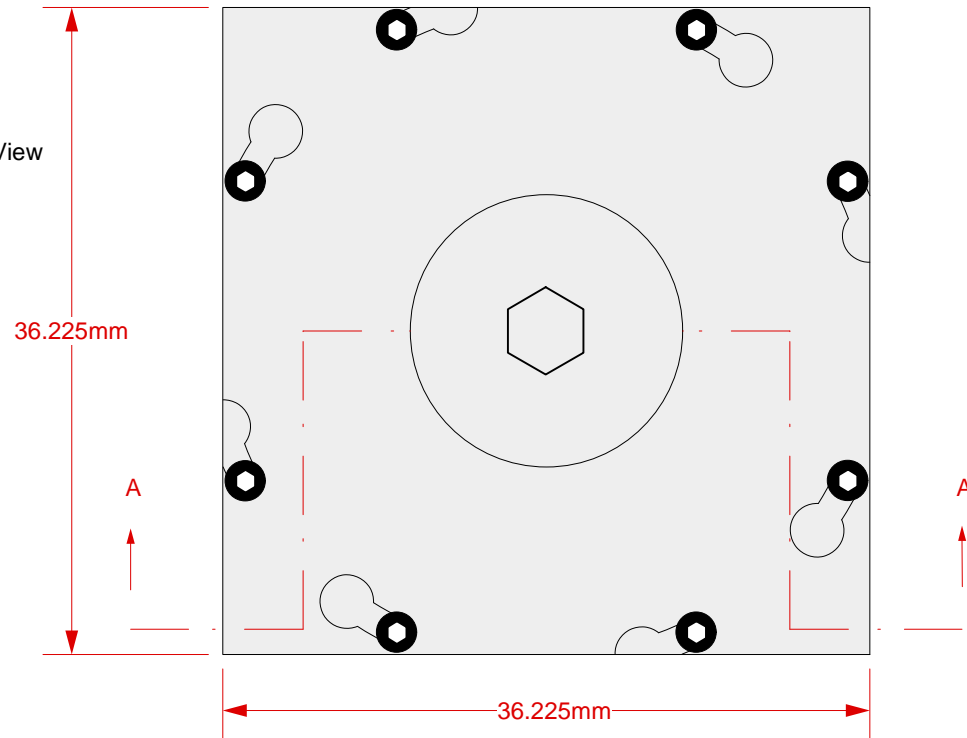


GHz BGA Socket - Direct mount, solderless

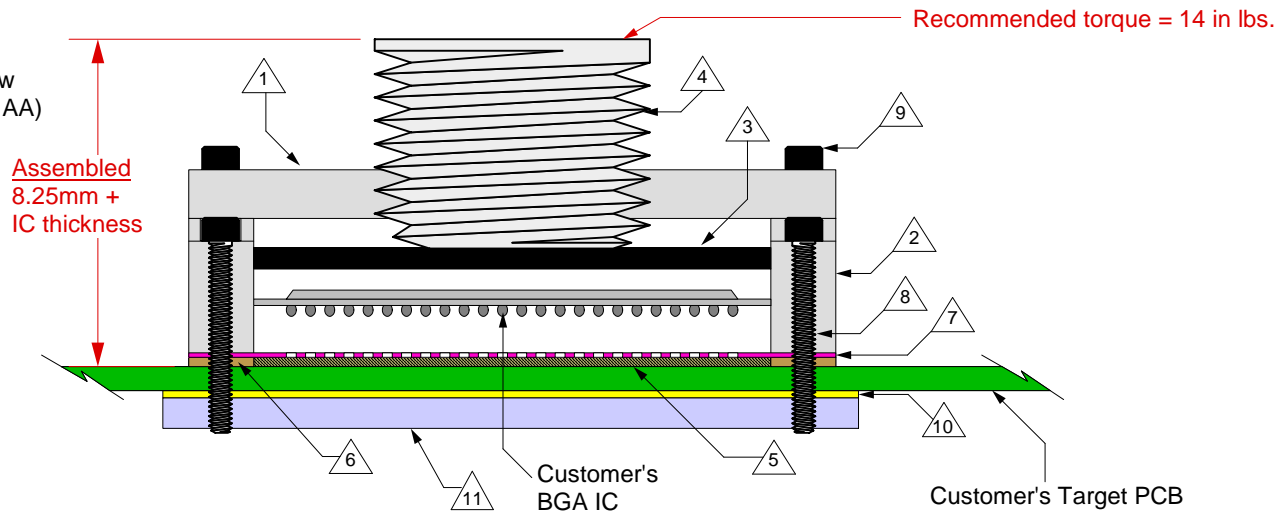
Top View



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 6.5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, 1.59mm thick.
- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-6096 Drawing

© 2009 IRONWOOD ELECTRONICS, INC.
11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

Drawing: Heidi Hansen

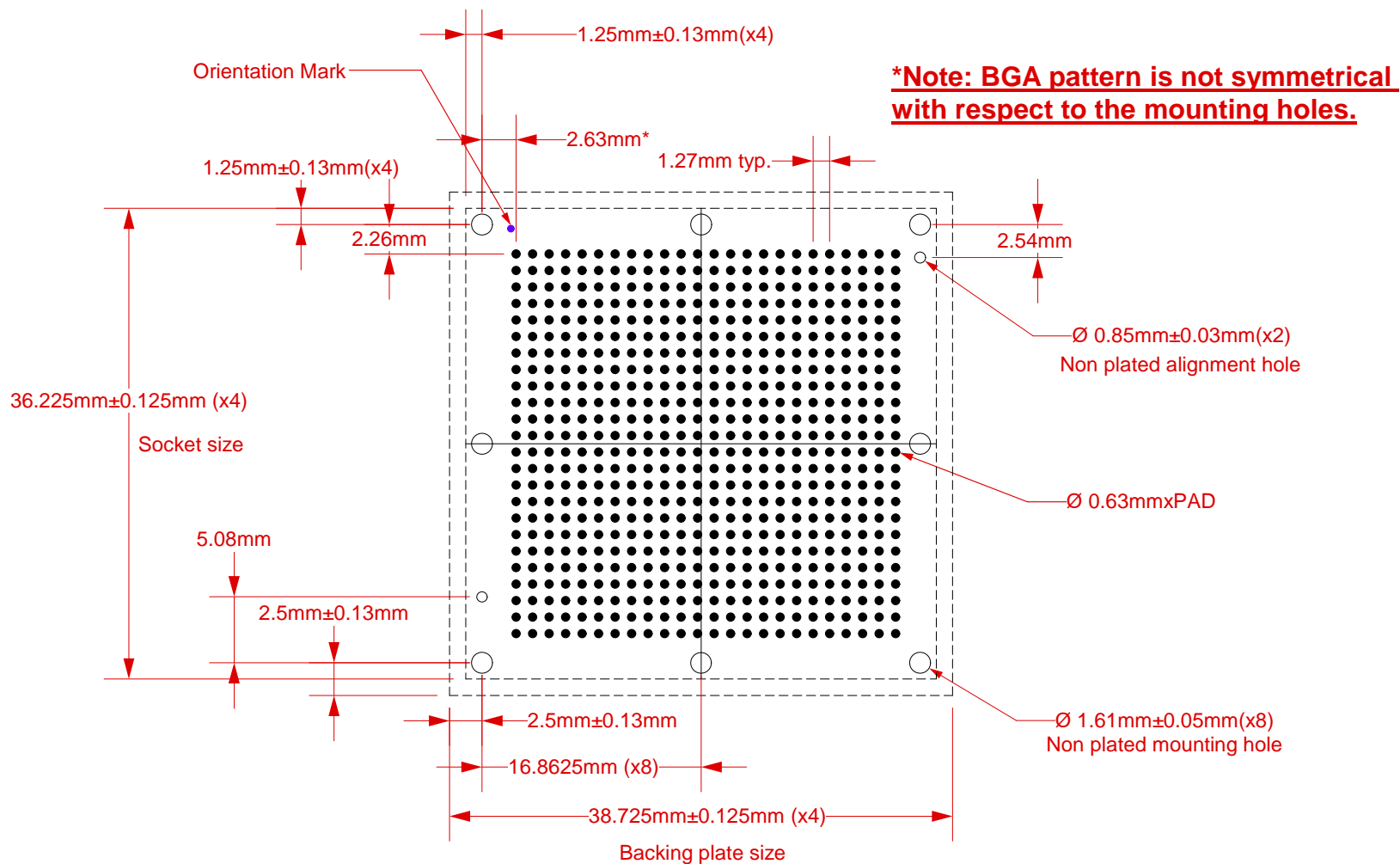
Date: 11/26/03

File: SG-BGA-6096 Dwg.mcd

Modified: 7/21/09, AE

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



Target PCB Recommendations


Total thickness: 2.4mm min.

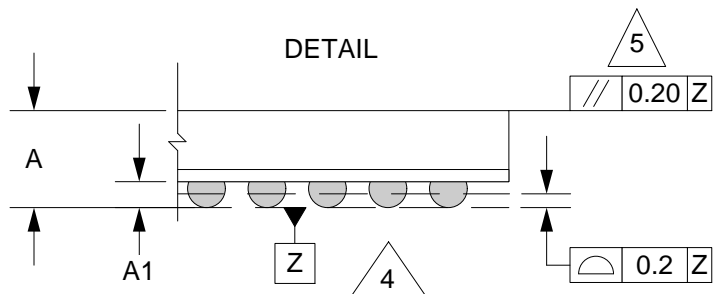
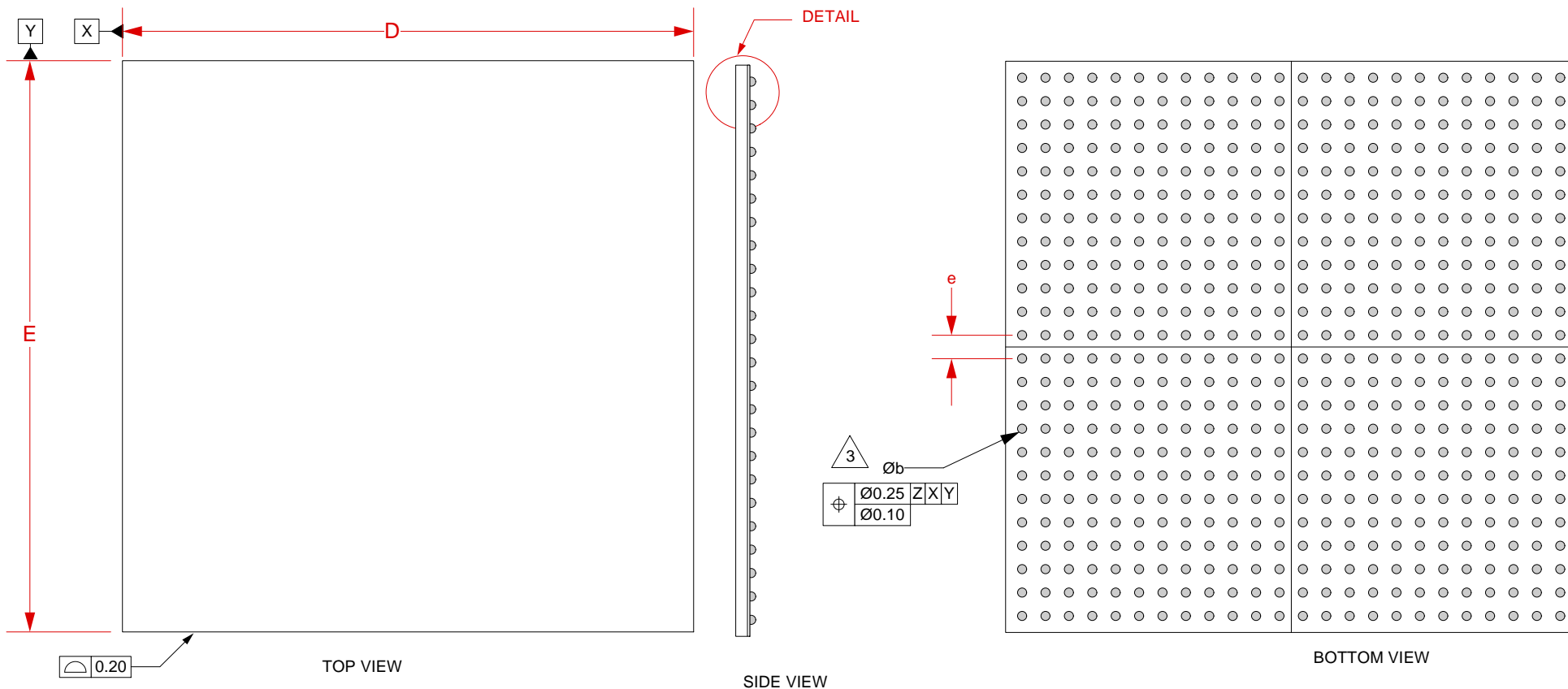
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SG-BGA-6096 Drawing</p>	<p>Status: Released</p>	<p>Scale: 2:1</p>	<p>Rev: B</p>
	<p>Drawing: Heidi Hansen</p>	<p>Date: 11/26/03</p>		<p>Modified: 7/21/09, AE</p>
<p>File: SG-BGA-6096 Dwg.mcd</p>				




1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

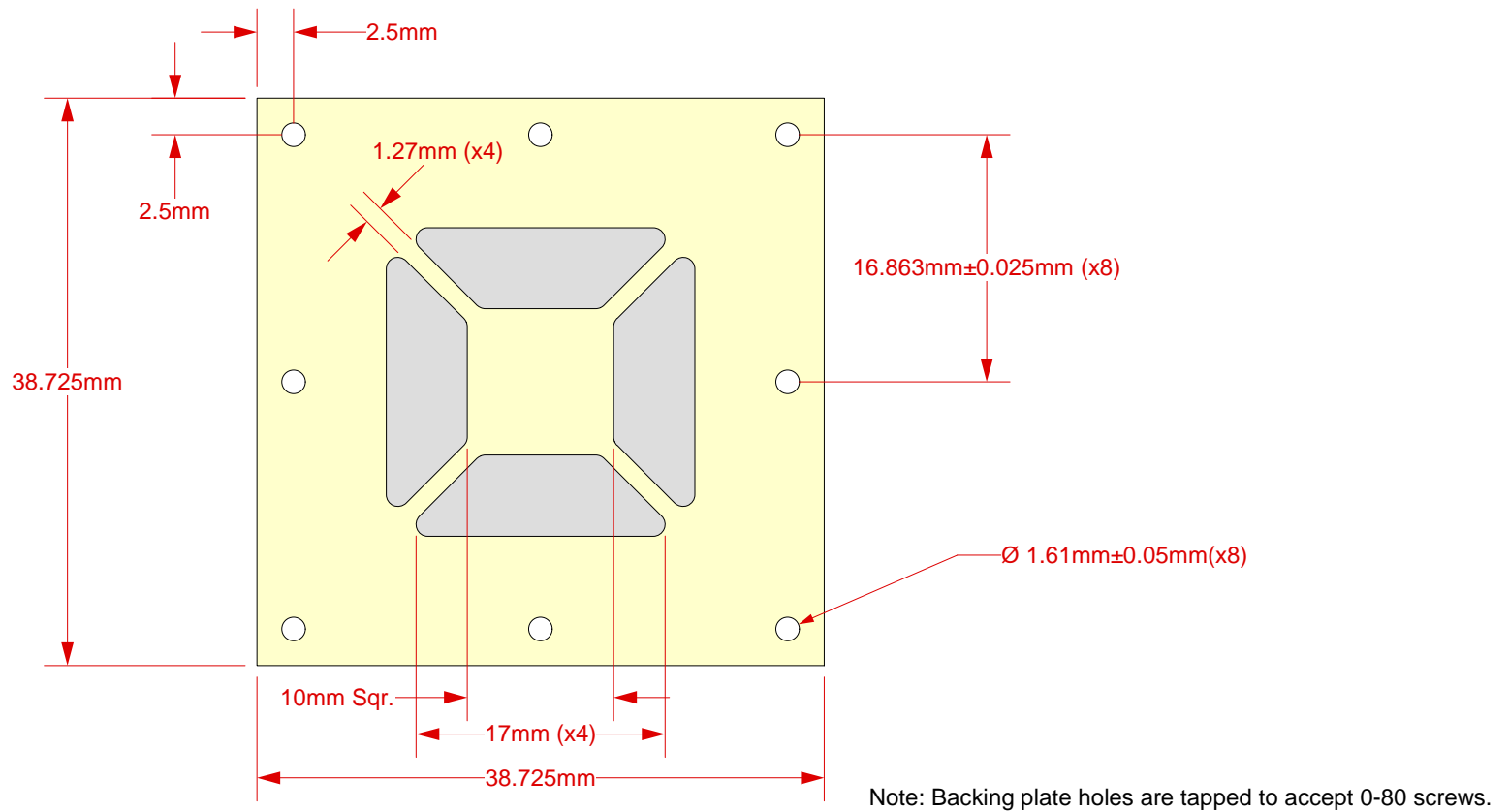
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.55
A1	0.5	0.7
b		0.90
D	31.00 BSC	
E	31.00 BSC	
e	1.27 BSC	

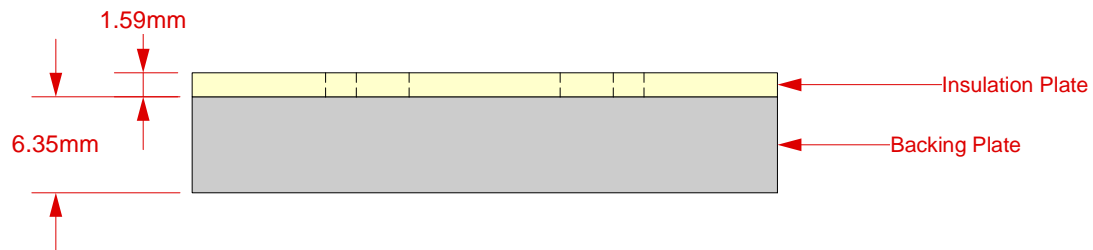
Array 24x24

 <p>SG-BGA-6096 Drawing © 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Status: Released	Scale: -	Rev: B
	Drawing: Heidi Hansen		Date: 11/26/03
	File: SG-BGA-6096 Dwg.mcd		Modified: 7/21/09, AE


Top View



Side View



Description: Insulation Plate and Backing Plate

	SG-BGA-6096 Drawing	Status: Released	Scale: -	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Heidi Hansen		Date: 11/26/03
		File: SG-BGA-6096 Dwg.mcd	Modified: 7/21/09, AE	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)